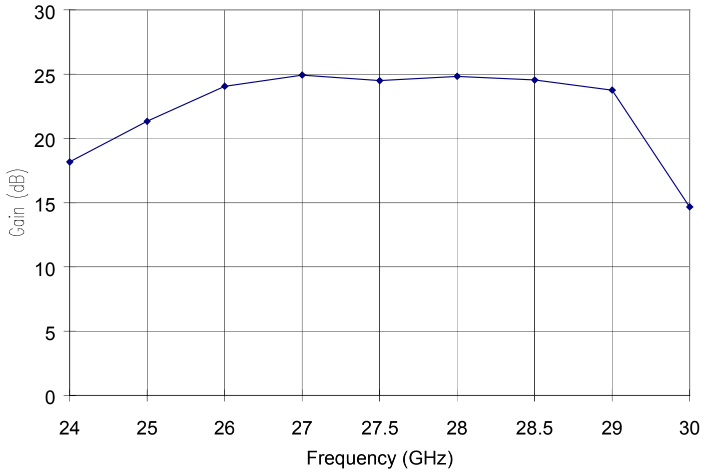
26-29 GHz Medium Power Amplifier TGA1081-EPU

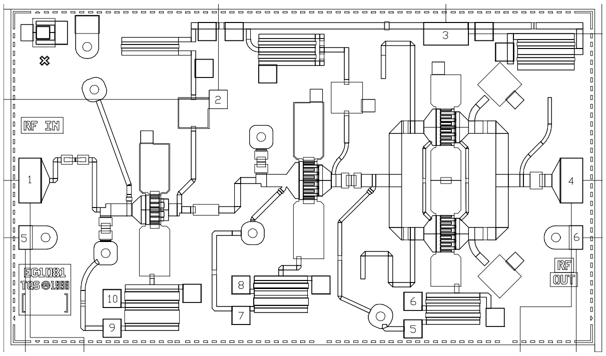
Key Features and Performance

- Production version of TGA9058
- 0.25um pHEMT Technology
- 26 GHz - 29 GHz Frequency Range
- Nominal Pout 22dBm @ 1dB GC
- Nominal SS Gain 24dB
- 5V, 315mA Bias

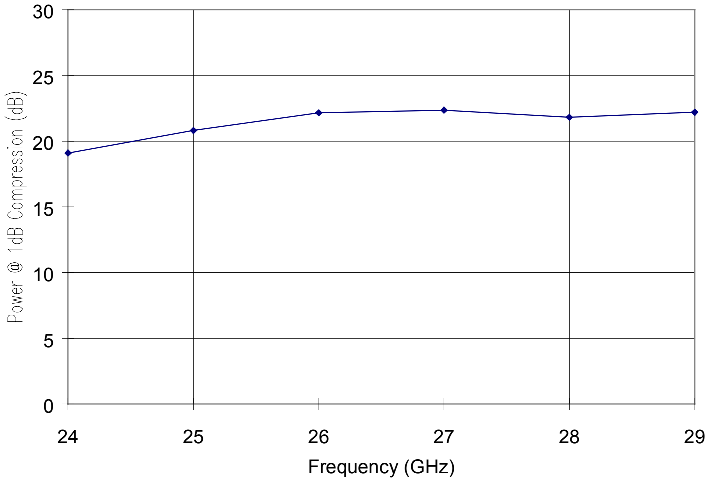
Primary Applications

- LMDS
- Point-to-Point Radio

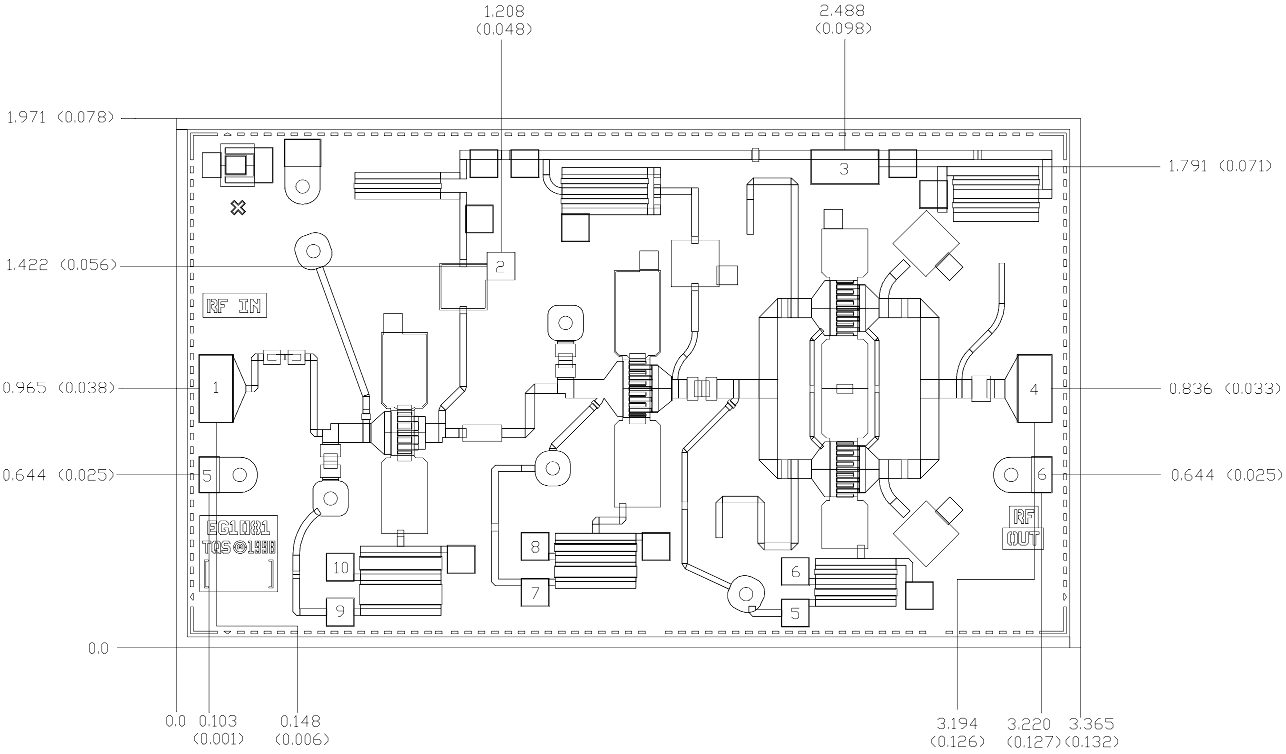




Chip Dimensions 3.365 mm x 1.971 mm



Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications subject to change without notice.



Units: millimeters (inches)
Thickness: 0.1016 (0.004) (reference only)
Chip edge to bond pad dimensions are shown to center of bond pad
Chip size tolerance: +/- 0.0508 (0.002)

Bond pad #1 (RF Input)	0.125 x 0.250 (0.005 x 0.010)
Bond pad #2 (Gnd)	0.103 x 0.105 (0.004 x 0.004)
Bond pad #3 (Vd)	0.125 x 0.250 (0.005 x 0.010)
Bond pad #4 (RF Output)	0.125 x 0.250 (0.005 x 0.010)
Bond pad #5 (Gnd)	0.075 x 0.136 (0.003 x 0.005)
Bond pad #6 (Gnd)	0.075 x 0.136 (0.003 x 0.005)

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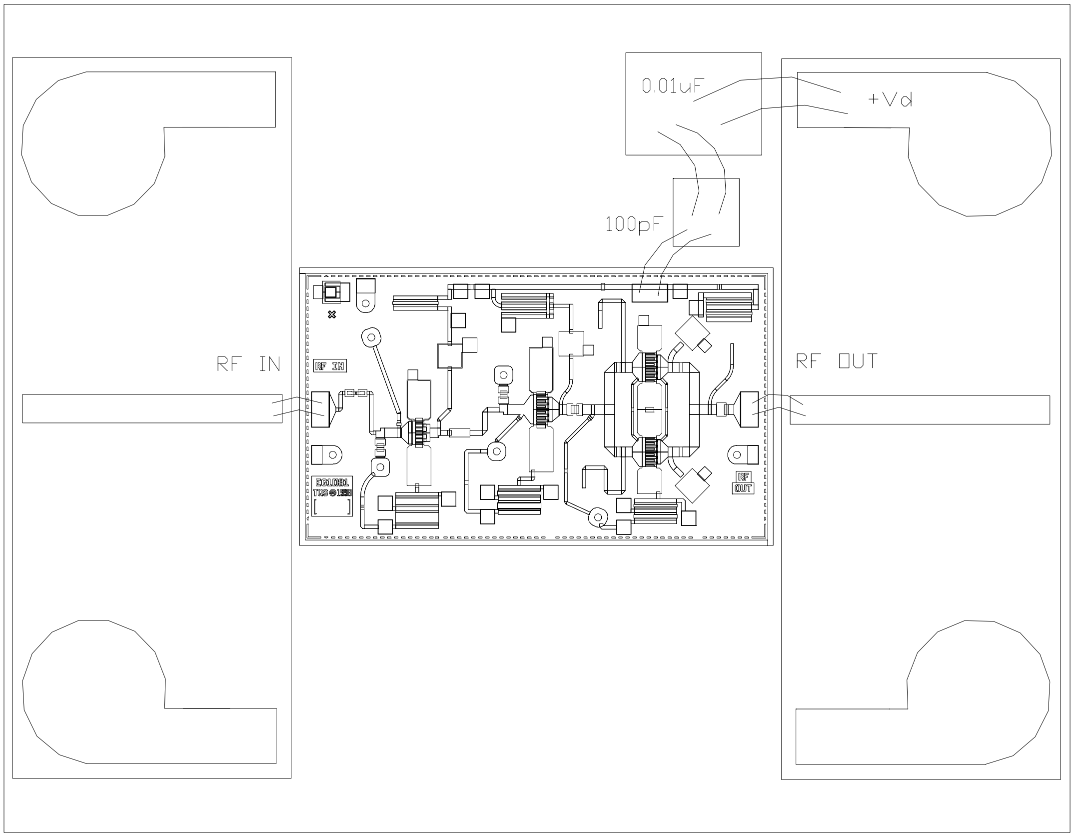

Assembly Diagram

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